Listing of the claims:

- 1. (Currently Amended) A device for the formation of gradient layers on substrates in a vacuum chamber by means of a particle flow formed from at least one plasma source or by vaporization, which is directed upon the substrate surface to be coated, wherein a mask having discretely located perforations is disposed between a particle source and a substrate, characterized in that said mask (1) of constant thickness can be moved oscillatorily by means of a drive along at least one axis with respect to said substrate (3) in a plane, and the ratio of free cross-sections of said perforations (2) being discretely present in said mask (1), and the intermediate web surfaces of said mask (1) per area unit is varied over at least one of the total surface, or on areas of said mask (1), and/or and the distance between the surface of said substrate (3) and said mask (1) is different in size over the total surface of surface areas.
- 2. (Currently Amended) A device according to claim 1, characterized in that said perforations (2) of said mask (1) each have identical free cross-sections and cross-sectional geometries.
- 3. (Currently Amended) A device according to claim 1 or elaim 2, characterized in that said free cross-sections of said perforations (2) are formed in one of a circular, hexagonal, octagonal or and elliptical form.
- 4. (Currently Amended) A device according to at least any one of the preceding claims, claim 1 characterized in that the ratio of said free cross-sections of said perforations (2) and said intermediate web surfaces per unit of area are continuously varied along at least one axis.
- 5. (Currently Amended) A device according to at least any one of the preceding claims claim 1, characterized in that said perforations are formed in a column and line arrangement within said mask (1).

- 6. (Original) A device according to claim 5, characterized in that said perforations are located offset to each other in the adjacent columns or lines.
- 7. (Currently Amended) A device according to at least any one of the preceding claims claim 1, characterized in that the distances of said perforations (2) are varied along at least one axis.
- 8. (Currently Amended) A device according to at least any one of the preceding claims claim 1, characterized in that the surface of said substrate (3) is at least one of aligned at an angle obliquely inclined with respect to said mask (1) and /or is curved.
- 9. (Currently Amended) A device according to at least any one of the preceding claims claim 1, characterized in that with a curved substrate surface the ratio of the free cross-sections of said perforations (2) and said intermediate web surface per unit of area takes into consideration at least one of the respective distance of said substrate surface and / or the inclination of said substrate surface and said mask (1).
- 10. (Currently Amended) A device according to at least any one of the preceding claims claim 1, characterized in that said mask (1) is at least one of aligned at an angle obliquely inclined with respect to the surface of said substrate (3) and / or is curved.
- 11. (Currently Amended) A device according to at least any one of the preceding claims, claim 1 characterized in that the direction of motion of said oscillatory motion is aligned in parallel to at least one of the respective lines and / or columns of perforations (2).

- 12. (Currently Amended) A device according to at least any one of the preceding claims claim 1, characterized in that the plasma source is a magnetron sputtering source.
- 13. (Currently Amended) A device according to at least any one of the preceding claims claim 1, characterized in that said substrate (3) and said mask (1) are movable together relative with respect to at least one of said plasma source and $\frac{1}{3}$ or said target (4).
- 14. (Currently Amended) A device according to claim 13, characterized in that said substrate (3) and said mask (1) rotate about a common axis of rotation.
- 15. (Currently Amended) A device according to at least any one of the preceding claims claim 1, characterized in that said drive for said oscillatory relative motion between said substrate (3) and said mask (1) is at least a piezo actuator.
- layers on substrates in a vacuum chamber by means of which a particle current formed from a plasma source or by means of evaporation of a target material will be directed through a mask located between said particle source and said substrate, in which perforations are formed, characterized in that the local thickness of said formed layer on the substrate surface is defined by at least one of predetermined locally adapted ratios of free cross-sections and said intermediate web surfaces per unit of area and / or by holding of particular distances between the surface of said substrate (3) and said mask (1), and said mask (1) having a constant thickness is moved oscillatorily along at least one axis relative to said substrate (3) in a plane.

- 17. (Currently Amended) A method according to claim 16, characterized in that with an oscillatory motion the path to be travelled between inversion points or during a circular path motion the diameter corresponds to the mean distance of the centre or centre of gravity of said perforations (2).
- 18. (Currently Amended) A method according to claim 16 or claim 17, characterized in that said relative motion or said circular path motion is performed in the plane of the mask.
- 19. (Currently Amended) A method according to at least any one of claim 16 to 18 claim 16, characterized in that a gradient multilayer system having at least two different layer materials is formed on the surface of said substrate (3).
- 20. (Currently Amended) A method according to at least any one of claims 16 to 19 claim 16, characterized in that one or several gradient layer(s) formed one above another will be formed on predetermined areas of the surface of said substrate (3).
- 21. (Currently Amended) A method according to at least any one of elaims 16 to 20 claim 16, characterized in that the layer(s) layer is (are) formed by means of magnetron sputtering.
- 22. (Currently Amended) A method according to <u>claim 16</u> at least any one of claims 16 to 21, characterized in that said substrate (3) and said mask (1) are moved together with respect to said particle source (4).
- 23. (Currently Amended) Use of a device according to any one of claims 1 to 15 claim 1 for the fabrication of X-ray optics elements.